



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D
<i>* : Required Field</i>			

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2016-05-17
<b>Contact Name *</b>	Refer to Supplier comment section	<b>Contact Title</b>	Refer to Supplier comment section
<b>Authorized Representative *</b>	Floriana San Biagio	<b>Representative Title</b>	AMG MD Champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**


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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	21CC*MV7GACA	A	MA1A	2016-05-17
	Amount	UoM	Unit type	ST ECOPACK Grade
	9.0	mg	Each	ECOPACK® 2
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nicke/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
LGA	2x 2x1	12	No lead	
Comment	Package: A0XS LGA 2X2X1 12LD PITCH 0.5MM; MDF valid for LSM303AHTR			

QueryList : ROHS directive 2011/65/EU _ANNEX IV	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description
7c-1	Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices

QueryList : REACH-17th December 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	21CC*MV7GACA									
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Dies	Other inorganic materials	3.085	mg	supplier	die	Silicon (Si)	7440-21-3		2.678	mg	868071	297556				
				supplier	metallisation	Aluminium (Al)	7429-90-5		0.016	mg	5186	1778				
				supplier	metallisation	Copper (Cu)	7440-50-8		0.028	mg	9076	3111				
				supplier	metallisation	Iron (Fe)	7439-89-6		0.020	mg	6483	2222				
				supplier	metallisation	Nickel (Ni)	7440-02-0		0.022	mg	7131	2444				
				supplier	metallisation	Tantalum (Ta)	7440-25-7		0.009	mg	2917	1000				
				supplier	metallisation	Titanium (Ti)	7440-32-6		0.003	mg	972	333				
				supplier	Passivation	Silicon Nitride (SiN)	12033-89-5		0.012	mg	3890	1333				
				supplier	passivation	Silicon Oxide	7631-86-9		0.152	mg	49271	16889				
				JIG - R	die glass coating	Lead-Borate Glass	65997-18-4	7c-I-Electrical and electron	0.145	mg	47002	16111				
				substrate	Other Organic Materials	1.977	mg	supplier	core material	Fiber glass	65997-17-3		0.341	mg	172511	37889
								supplier	core material	Bismaleimide (B)	13676-54-5		0.115	mg	58178	12778
supplier	core material	Triazine (T)	25722-66-1						0.115	mg	58178	12778				
supplier	core material	Epoxy Cresol Novolak	29690-82-2						0.079	mg	39966	8778				
supplier	core material	Epoxyde Bisphenol A Resin	25068-38-6						0.079	mg	39966	8778				
JIG - I	core material	Brominated compound	68541-56-0						0.055	mg	27824	6111				
supplier	core material	Amorphous Silica	7631-86-9						0.004	mg	2024	444				
supplier	core material	Magnesium silicate	13776-74-4						0.004	mg	2024	444				
supplier	Solder mask	Barium sulfate	7727-43-7						0.040	mg	20236	4444				
supplier	Solder mask	Acrylic resin	9003-01-4						0.062	mg	31366	6889				
supplier	Solder mask	Epoxy resin	29690-82-2						0.048	mg	24283	5333				
supplier	Solder mask	Biphenyl epoxy resin	85954-11-6						0.030	mg	15177	3333				
supplier	Solder mask	Talc containing no asbestiform fibers	14807-96-6						0.023	mg	11636	2556				
supplier	Solder mask	Methoxymethylethoxy propanol	34590-94-8						0.007	mg	3541	778				
supplier	Solder mask	Amorphous silica	7631-86-9						0.004	mg	2024	444				
supplier	Solder mask	3-methyl-methoxy-buthyl	103429-90-9						0.003	mg	1518	333				
supplier	Solder mask	Silica Cristobalite	14464-46-1						0.002	mg	1012	222				
supplier	Solder mask	Morpholine derivative	Proprietary						0.001	mg	506	111				
supplier	metallisation	Copper (Cu)	7440-50-8						0.954	mg	482627	106000				
Nickel (Ni)	supplier	metallisation	Nickel (Ni)					7440-02-0		0.008	mg	4250	933			
Precious metals	supplier	metallisation	Gold (Au)					7440-57-5		0.001	mg	577	127			
Precious metals	supplier	metallisation	Palladium (Pd)					7440-05-3		0.001	mg	577	127			
Die attach	Other inorganic materials	0.285	mg					supplier	tape	epoxy resin	Proprietary		0.181	mg	635088	20111
								supplier	tape	polyolefin	9003-07-0		0.090	mg	315789	10000
				supplier	tape	Diphenol Propane Diglycidyl Ether	1675-54-3		0.014	mg	49123	1556				
				supplier	tape	amorphous silica	7631-86-9		0.017	mg	414634	1889				
Die attach 2	Other inorganic materials	0.041	mg	supplier	tape	epoxy resin	25038-59-9		0.010	mg	243902	1111				
				supplier	tape	Acrylic resin	9003-01-4		0.007	mg	170732	778				
				supplier	tape	Epoxyde Bisphenol A Resin	25068-38-6		0.007	mg	170732	778				
				supplier	wire	Gold (Au)	7440-57-5		0.223	mg	991111	24778				
Bonding wire	Precious metals	0.225	mg	supplier	wire	Palladium (Pd)	7440-05-3		0.002	mg	8889	222				
				supplier	mold compound	Silica, vitreous	60676-86-0		2.692	mg	794804	299111				
encapsulation	Other Organic Materials	3.387	mg	supplier	mold compound	Silica	7631-86-9		0.339	mg	100089	37667				
				supplier	mold compound	Epoxy Resin	Proprietary		0.135	mg	39858	15000				
				supplier	mold compound	Epoxyde Bisphenol A Resin	25068-38-6		0.119	mg	35134	13222				
				supplier	mold compound	Phenol Resin	Proprietary		0.085	mg	25096	9444				
				supplier	mold compound	Carbon black	1333-86-4		0.017	mg	5019	1889				
				supplier	mold compound											